

AMENDMENTS TO THE CLAIMS

The listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. **(Currently Amended)** A transceiver module for use in a fiber-optic network system comprising:

a transceiver module casing;

a receiver subassembly disposed in the transceiver module casing; and

a transmitter optical subassembly disposed in the transceiver module casing, wherein the transmitter optical subassembly includes a header assembly having enclosed therein:

a thermoelectric cooler (TEC); and

a laser component capable of transmitting optical data a distance greater than 10 kilometers.

2. **(Currently Amended)** A transceiver module as set forth in claim 1, wherein the laser component is optimized to operate at a ~~an~~ elevated temperature greater than 25 degrees Celsius.

3. **(Original)** A transceiver module as set forth in claim 1, further comprising a bail release coupled to an anterior end of the transceiver module casing.

4. **(Currently Amended)** A transceiver module as set forth in claim 1, wherein the transceiver module is constructed so as to comply with one or more of the Small Form-factor-SFF, Small Form-factor Pluggable-SFP, and 10-Gigabit Small Form-factor Pluggable XFP Multi Source Agreements.

5. **(Currently Amended)** A transceiver module as set forth in claim 1, wherein the laser ~~component~~ is an externally modulated laser and the distance is in a range of about 10 kilometers to 160 kilometers.

6. **(Currently Amended)** A transceiver module as set forth in claim 1, wherein the laser ~~component~~ is an externally modulated laser and the distance is in a range of 40 kilometers to 80 kilometers in a 10 Gb/s system.

7. **(Original)** A transceiver module as set forth in claim 1, wherein the transmitter optical subassembly comprises a platform having a conductive pathway extending through the platform and wherein a portion of the platform is exposed external to the transmitter optical subassembly.

8. **(Original)** A transceiver module as set forth in claim 7, wherein the conductive pathway comprises a plurality of isolated traces of a sufficient number to at least provide control signals to an integrated circuit laser driver.

9. **(Original)** A transceiver module as set forth in claim 7, wherein the conductive pathway forms a transmission line adapted to match the impedance of a component connected to a first end of the conductive pathway with a source intended to drive the component, wherein the source is intended to be connected to a second end of the conductive pathway.

10. **(Original)** A transceiver module for transmitting fiber optic data in a fiber optic system, the transceiver module comprising:

a transceiver module casing; and

a transmitter optical subassembly disposed in the transceiver module casing, wherein the transmitter optical subassembly includes a header assembly having enclosed therein:

an externally modulated laser (EML) for transmission of optical data a distance greater than 40 kilometers; and
a thermoelectric cooler (TEC) for cooling the externally modulated laser.

11. **(Original)** A transceiver module as set forth in claim 10, wherein the distance is in a range of 40 kilometers to 160 kilometers.

12. **(Currently Amended)** A transceiver module as set forth in claim 10, wherein the externally modulated laser is optimized to operate at a ~~an elevated~~ temperature of about 40 degrees Celsius.